**MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS**

**DPAK3**  
CASE 369AK  
ISSUE O

**DATE)**  
30 SEP 2016

---

**NOTES:** UNLESS OTHERWISE SPECIFIED
A) NOT COMPLIANT TO JEDEC TO-252 VARIATION AB
B) ALL DIMENSIONS ARE IN MILLIMETER
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D) LAND PATTERN PER IPC7351A STANDARD
TO228P991X239-3N
E) DOES NOT COMPLY TO JEDEC STANDARD VALUE.

---

**DOCUMENT NUMBER:** 98AON13809G

**DESCRIPTION:** DPAK3

---

**Electronic versions are uncontrolled except when accessed directly from the Document Repository.**
**Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.**

© Semiconductor Components Industries, LLC, 2019